

1U Optimized

Key Features

3rd Gen Intel® Xeon® Scalable processors, Single Socket LGA-4189 (Socket P+) supported, CPU TDP supports Up to 270W TDP

Intel® C621A

Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz; Up to 2TB 3DS ECC LRDIMM, DDR4-3200MHz Up to 2TB Intel® Optane™ Persistent Memory, in 8 DIMM slots

1 PCI-E 4.0 x16,

2 PCI-E 4.0 NVMe x8 Internal Port(s) M.2 Interface: 2 SATA/PCI-E 3.0 x4 M.2 Form Factor: 2280/22110

M.2 Key: M-Key

Intel® C621A controller for 10 SATA3 (6 Gbps) ports; RAID 0,1,5,10

Dual LAN with Intel® i350 Gigabit Ethernet Controller

Supports 4x NVMe drives via Slim SAS connectors

Product SKUs	
MBD-X12SPO-F	X12SPO-F
Physical Stats	
Form Factor	ATX
Dimension	■ 12" x 10" (30.48cm x 25.4cm)
Processor	
CPU	 3rd Gen Intel® Xeon® Scalable processors Single Socket LGA-4189 (Socket P+) supported, CPU TDP supports Up to 270W TDP
Core	■ Up to 40 cores
System Memory Memory	∎ 8 DIMM slots
	 8 DIMM slots Up to 2TB Intel® Optane[™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz
Memory	 Up to 2TB Intel® Optane [™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM,
Memory Capacity	 Up to 2TB Intel® Optane™ Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz 3200/2933/2666MHz ECC , DDR4
Memory Capacity Memory Type	 Up to 2TB Intel® Optane[™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz 3200/2933/2666MHz ECC , DDR4 LRDIMM (3DS), RDIMM (3DS)
Memory Capacity Memory Type DIMM Sizes Memory	 Up to 2TB Intel® Optane[™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz 3200/2933/2666MHz ECC , DDR4 LRDIMM (3DS), RDIMM (3DS) 8GB, 16GB, 32GB, 64GB, 128GB, 256GB
Memory Capacity Memory Type DIMM Sizes Memory Voltage	 Up to 2TB Intel® Optane[™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz 3200/2933/2666MHz ECC , DDR4 LRDIMM (3DS), RDIMM (3DS) 8GB, 16GB, 32GB, 64GB, 128GB, 256GB 1.2V
Memory Capacity Memory Type DIMM Sizes Memory Voltage Error Detection	 Up to 2TB Intel® Optane[™] Persistent Memory 200 Series Up to 2TB 3DS ECC LRDIMM, DDR4- 3200MHz; Up to 2TB 3DS ECC RDIMM, DDR4-3200MHz 3200/2933/2666MHz ECC , DDR4 LRDIMM (3DS), RDIMM (3DS) 8GB, 16GB, 32GB, 64GB, 128GB, 256GB 1.2V

Configurations	ACPI Power Management, CPU thermal trip support for processor protection
PC Health Monitoring	
Voltage	 VBAT, System temperature, Monitors CPU voltages, HT, Chassis intrusion header, 3.3V standby, +5V standby, +5V, +3.3V, +12V, +1.8V, 7-fan status
LED	 UID/Remote UID Suspend static indicator LED CPU / System Overheat LED
Temperature	CPU thermal trip supportPECI
FAN	 7x4-pin fan headers (up to 7 fans) System level control PWM fan speed control Fan speed control Overheat LED indication
Other Features	 WOL, UID, RoHS, Chassis intrusion header, Chassis intrusion detection, ATX Power connector, ACPI power

Input / Output	
SATA	■ 10 SATA3 (6Gbps) port(s)
LAN	2 RJ45 Gigabit Ethernet LAN ports
USB	 6 USB 2.0 port(s) (4 via header; 2 rear) 5 USB 3.2 Gen1 port(s) (2 via header; 2 rear; 1 type A)
Video Output	∎ 1 VGA port(s)
Serial Port	2 COM Port(s) (1 header; 1 rear)
DOM	 2 SATA <u>DOM</u> (Disk on Module) power connector support
ТРМ	1 TPM Header

ASPEED AST2600 BMC

ASPEED AST2600 BMC

Controller

Dual LAN with Intel® i350 Gigabit Ethernet

IPMI

Graphics

Network Controllers

Operating Environment		
Operating Temperature Range	∎ 0°C - 50°C (32°F - 122°F)	
Non-Operating Temperature Range	∎ -40°C - 70°C (-40°F - 158°F)	
Operating Relative Humidity Range	∎ 10% - 85% (non-condensing)	
Non Operating Relative Humidity Range	∎ 10% - 95% (non-condensing)	

management, RoT

System BIOS **BIOS Type** AMIUEFI **BIOS Features** ACPI 6.2 SMBIOS 3.0 or later UEFI 2.7 Management SuperDoctor® 5, <u>SUM</u>, KVM with dedicated LAN, <u>SPM</u>, Intel® Node Manager, <u>SSM</u>, Software IPMI2.0, Watchdog Power-on mode for AC power recovery, ACPI Power Management CPI I thermal Power Configurations

1 PCI-E 4.0 x16

Key: M-Key

M.2 Interface: 2 SATA/PCI-E 3.0 x4

Form Factor: 2280/22110

Expansion Slots

PCI-E

M.2